



The Future of Instrument Making Research

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Deadline for manuscript
submissions:

30 September 2024

Message from the Guest Editors

Musical instrument making research is undergoing a veritable revolution. With new computational methods available, researchers are getting used to busying themselves at the workbench, and each day, instrument makers are more comfortable with the concepts of acoustics and the application of artificial intelligence. This Special Issue will be an accompanying volume for the second Mondo Acustica conference to be held in Cremona on the 25th and 26th of September, 2024. The topic of the conference is the future of instrument making research, encompassing new ways of crafting, measuring and studying stringed instruments. The development of musical instruments has had a parallel history from science; Galileo's father was a lute player and researched string properties in his basement in Pisa. This year, we are meeting in Cremona to build a future where science and instrument making speak more freely and learn to understand one another. Topics range from timbre characterization, new methods for the simulation of musical instruments and cutting-edge technology for instrument manufacture, as well as new methodologies for their conservation.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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